

**Shinkawa to Release a High-speed, High-accuracy Flip Chip Bonder YSB55w**

Shinkawa Ltd. (President: Takashi Nagano, Headquarters: 51-1, Inadaira 2-chome, Musashi-Murayama-shi, Tokyo, Japan) will release in December 2015 a high-speed and high-accuracy flip chip bonder YSB55w, which is under development by Yamaha Motor Co., Ltd.

In recent years, the market of smartphones and wearable devices has expanded the production scale for semiconductors. Among them, flip chip packages that enable smaller, thinner, more energy efficient and functionally superior device modules have been increasingly utilized, creating demand for high-productivity and high accuracy flip chip bonding more than ever.

To meet this market demand, the new model YSB55w pursues high-productivity and high-accuracy by employing a high-rigidity frame, a dual bonding head and a newly-developed high-resolution chip recognition camera. It almost triples the productivity of existing models, and achieves high-precision bonding accuracy at the top of the industry.

**【Features of YSB55w】**

- (1) High-speed bonding at a top-level speed of 13,000 UPH (＊) (under optimal conditions, includes processing time)
  - (2) Bonding accuracy of  $\pm 5\mu\text{m}$ (3 $\sigma$ ) with the newly-developed high-resolution chip recognition camera
  - (3) Compact heads which carry out high-accuracy force control
  - (4) Capable of handling a wide range of chip sizes between 2-30mm
  - (5) Easy-to-configure dipping station
- ＊UPH : Units Per Hour



**【YSB55w】**

The YSB55w will be exhibited in the SEMICON Taiwan 2015 held at the Taipei Nangang Exhibition Center for three days from September 2, 2015.

- Other Product Line-ups  
Wire Bonder, Die Bonder

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